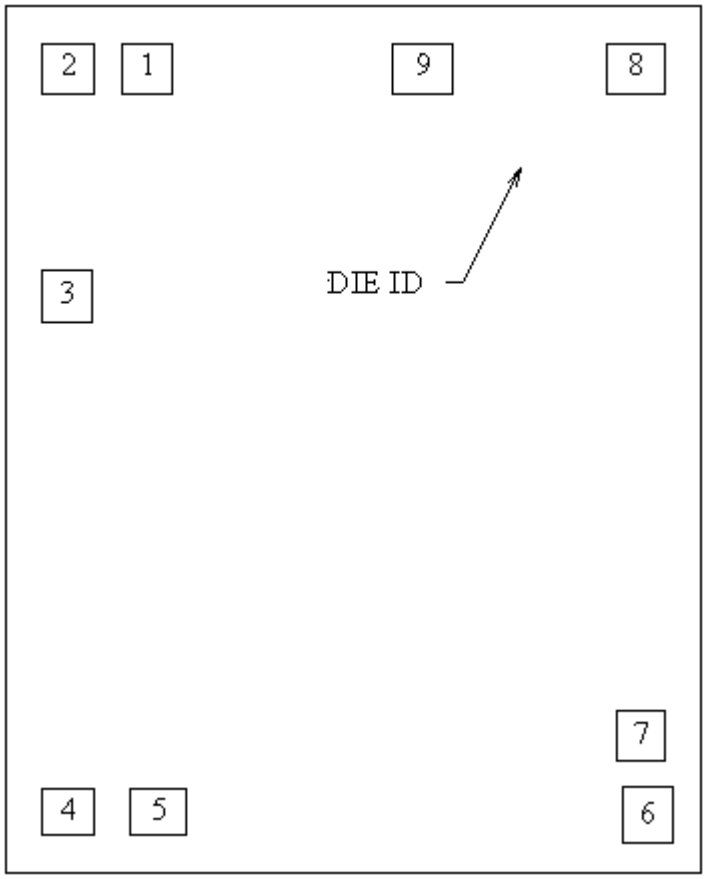
LM118 MD8 MW8
OPERATIONAL AMPLIFIERS

January 29,2007

DIE LAYOUT (F-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	118F	Bond Pad Opening Size (min)	117µm x 104µm
Die Step	F	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1549µm x 1930µm 61.0mils x 76.0mils	Back Side Connection	-V
Thickness	406µm Nominal		
Min Pitch	174µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (F -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
BAL/COMP-1	1	-460	828	112	x	112
INPUT -	2	-635	828	117	x	112
INPUT +	3	-638	319	112	x	119
V -	4	-635	-832	117	x	104
BAL/COMP-3	5	-436	-832	124	x	104
NC	6	657	-839	109	x	124
OUTPUT	7	641	-660	104	x	112
V +	8	629	828	130	x	112
COMP -2	9	154	828	130	x	112

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